

	Hits	Search Text	DBs
22	22	((substrate or wafer or device or plate) same ((spray\$3 near9 coat\$4) or (nozzle near12 spray\$3) or dispens\$5 or discharg\$4) same (photoresist or resist)) and (((nozzle or spray) near26 (moving or rotat\$4 or spin\$4) near28 (vary\$4 or variable or different) near29 (speed or velocity or velocit\$4 or rate)) same (photoresist or resist) same (coat\$3 or film or form\$3 or deposit\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
23	18	((substrate or wafer or device or plate) same ((spray\$3 near9 coat\$4) or (nozzle near12 spray\$3) or dispens\$5 or discharg\$4) same (photoresist or resist) same (across or diameter or center)) and (((nozzle or spray) near26 (moving or rotat\$4 or spin\$4) near28 (vary\$4 or variable or different) near29 (speed or velocity or velocit\$4 or rate)) same (photoresist or resist) same (coat\$3 or film or form\$3 or deposit\$4 or layer))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hit s	Search Text	DBs
24	2	((substrate or wafer or device or plate) same ((spray\$3 near9 coat\$4) or (nozzle near12 spray\$3) or dispens\$5 or discharg\$4) same (photoresist or resist)) and (((nozzle or spray) near26 (moving or rotat\$4 or spin\$4) near28 (vary\$4 or variable or different) near29 (speed or velocity or velocit\$4 or rate)) same (photoresist or resist) same (coat\$3 or film or form\$3 or deposit\$4)) and ((substrate or wafer or template) near22 (circular or shape or geometr\$4))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
25	25	((substrate or wafer or device or plate) same ((spray\$3 near9 coat\$4) or (nozzle near12 spray\$3) or dispens\$5) same (photoresist or resist or polymide or cur\$4) same solution same (coat\$3 or film or form\$3 or deposit\$4) same viscos\$5) and ((substrate or wafer or platen or device) same surface same (prim\$2 or (treat\$5 near6 solution) or treat\$4 or pre\$3treat\$4) same (nozzle or spray or dispens\$4) same (rotat\$4 or mov\$5 or spin\$4)) and ((substrate or wafer) same (rotat\$4 or sin\$4 or mov\$5))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
26	0	((substrate or wafer or device or plate) same ((spray\$3 near9 coat\$4) or (nozzle near12 spray\$3)) same (photoresist or resist or polyimide) same solution same solid same (coat\$3 or film or form\$3 or deposit\$4) same viscos\$5 same centipoises)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
27	2	((substrate or wafer or device or plate) same ((spray\$3 near9 coat\$4) or (nozzle near12 spray\$3)) same (photoresist or resist or polyimide) same solution same (coat\$3 or film or form\$3 or deposit\$4) same viscos\$5 same centipoises)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
28	2	((substrate or wafer or device or plate) same ((spray\$3 near9 coat\$4) or (nozzle near12 spray\$3)) same (photoresist or resist or polyimide) same solution same (coat\$3 or film or form\$3 or deposit\$4) same (viscos\$5 near16 (centipoises or poises)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
29	3	((substrate or wafer or device or plate) same ((spray\$3 near9 coat\$4) or (nozzle near12 spray\$3)) same (photoresist or resist or polyimide) same (viscos\$5 near16 (centipoises or poises)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
30	5	((spray\$3 near9 coat\$4) or (nozzle near12 spray\$3)) same (photoresist or resist or polyimide) same (viscos\$5 near16 (centipoises or poises)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
31	82	((coat\$4 or film or form\$4 or layer or spray\$4) same (photoresist or resist or polyimide) same (viscos\$5 near16 (centipoises or poises)) same thickness)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB